

2SJ363-VB Datasheet

P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY

V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A) ^d	Q_g (Typ.)
- 30	0.050 at $V_{GS} = - 10$ V	- 7.6	13 nC
	0.056 at $V_{GS} = - 4.5$ V	- 6.0	

FEATURES

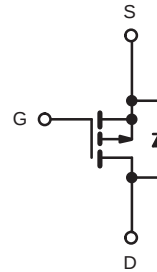
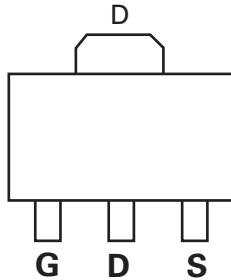
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- 100 % R_g Tested



RoHS
COMPLIANT
HALOGEN
FREE
Available

APPLICATIONS

- Load Switch
- Battery Switch



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	- 30	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current ($T_J = 150\text{ }^\circ\text{C}$)	$T_C = 25\text{ }^\circ\text{C}$	- 7.6	A
	$T_C = 70\text{ }^\circ\text{C}$	- 5.8	
	$T_A = 25\text{ }^\circ\text{C}$	- 6.0 ^{a, b}	
	$T_A = 70\text{ }^\circ\text{C}$	- 5.2 ^{a, b}	
Pulsed Drain Current	I_{DM}	- 35	
Continuous Source-Drain Diode Current	$T_C = 25\text{ }^\circ\text{C}$	- 3.5	
	$T_A = 25\text{ }^\circ\text{C}$	- 2.1 ^{a, b}	
Maximum Power Dissipation	$T_C = 25\text{ }^\circ\text{C}$	6.5	W
	$T_C = 70\text{ }^\circ\text{C}$	3.5	
	$T_A = 25\text{ }^\circ\text{C}$	2.5 ^{a, b}	
	$T_A = 70\text{ }^\circ\text{C}$	1.6 ^{a, b}	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 150	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{a, c}	$t \leq 10$ s	R_{thJA}	40	50	$^\circ\text{C/W}$
Maximum Junction-to-Foot	Steady State	R_{thJF}	24	30	

Notes:

- Surface mounted on 1" x 1" FR4 board.
- $t = 10$ s.
- Maximum under Steady State conditions is $95\text{ }^\circ\text{C/W}$.
- Package limited.

SPECIFICATIONS T _J = 25 °C, unless otherwise noted						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 30			V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	I _D = - 250 μA		- 31		mV/°C
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J			4.5		
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA	- 1.0		- 2.5	V
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V			- 1	μA
		V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C			- 5	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≤ - 5 V, V _{GS} = - 10 V	- 20			A
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 10 V, I _D = - 7.0 A		0.050		Ω
		V _{GS} = - 4.5 V, I _D = - 5.6 A		0.056		
Forward Transconductance ^a	g _{fs}	V _{DS} = - 15 V, I _D = - 7.0 A		18		S
Dynamic ^b						
Input Capacitance	C _{iss}	V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz		1355		pF
Output Capacitance	C _{oss}			180		
Reverse Transfer Capacitance	C _{rss}			145		
Total Gate Charge	Q _g	V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 7.0 A		25	38	nC
		V _{DS} = - 15 V, V _{GS} = - 4.5 V, I _D = - 7.0 A		13	20	
Gate-Source Charge	Q _{gs}			3.5		
Gate-Drain Charge	Q _{gd}			5.5		
Gate Resistance	R _g	f = 1 MHz	0.4	2.0	4.0	Ω
Turn-On Delay Time	t _{d(on)}	V _{DD} = - 15 V, R _L = 2.7 Ω I _D ≡ - 5.6 A, V _{GEN} = - 10 V, R _g = 1 Ω		10	20	ns
Rise Time	t _r			13	20	
Turn-Off DelayTime	t _{d(off)}			23	35	
Fall Time	t _f			9	18	
Turn-On Delay Time	t _{d(on)}	V _{DD} = - 15 V, R _L = 2.7 Ω I _D ≡ - 5.6 A, V _{GEN} = - 4.5 V, R _g = 1 Ω		38	57	
Rise Time	t _r			89	134	
Turn-Off DelayTime	t _{d(off)}			22	33	
Fall Time	t _f			11	17	
Drain-Source Body Diode Characteristics						
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			- 6.5	A
Pulse Diode Forward Current	I _{SM}				- 30	
Body Diode Voltage	V _{SD}	I _S = - 5.6 A, V _{GS} = 0 V		- 0.71	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}	I _F = - 5.6 A, dI/dt = 100 A/μs, T _J = 25 °C		22	33	ns
Body Diode Reverse Recovery Charge	Q _{rr}			17	26	nC
Reverse Recovery Fall Time	t _a			13		ns
Reverse Recovery Rise Time	t _b			9		

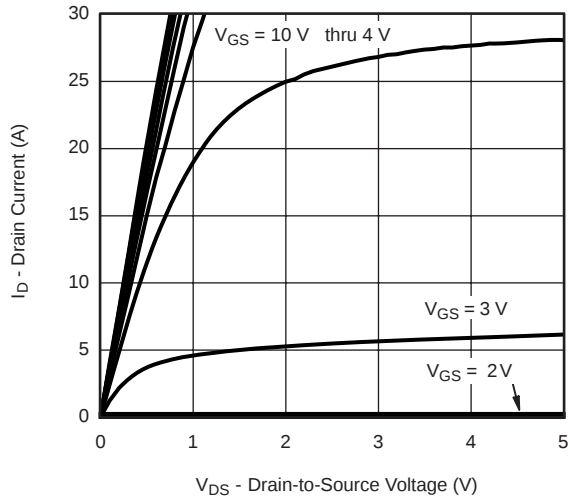
Notes:

a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

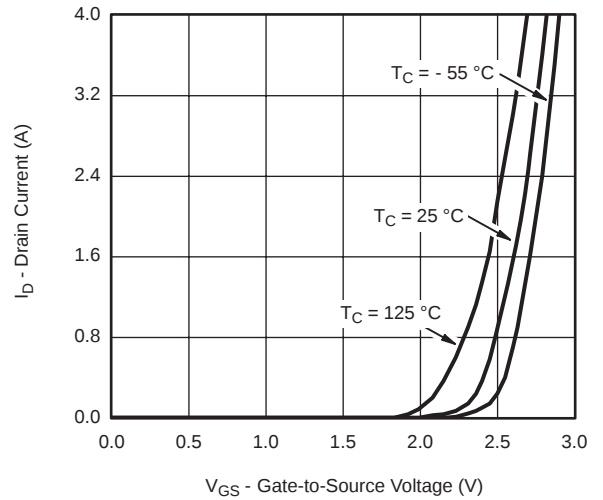
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

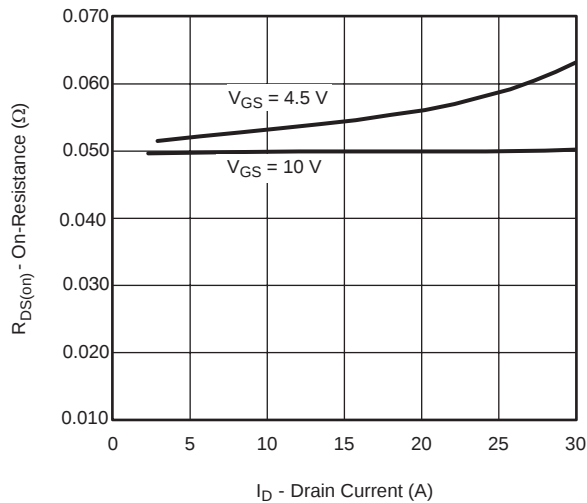
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



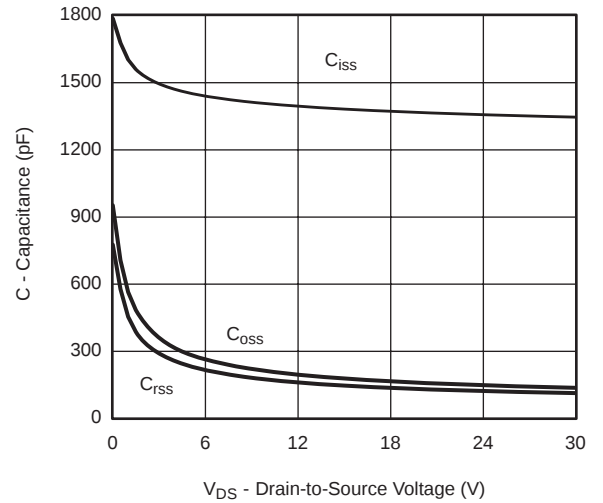
Output Characteristics



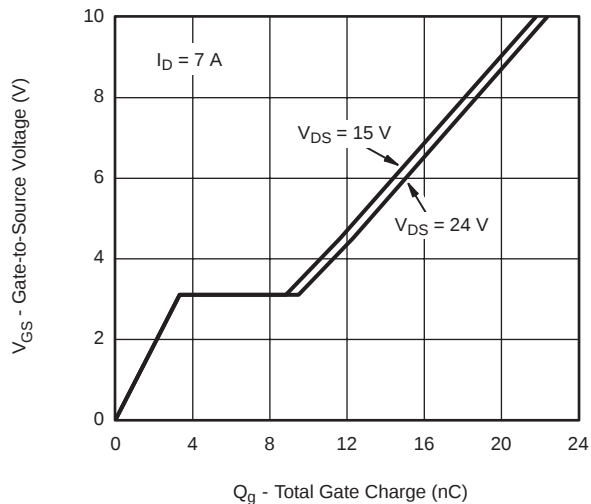
Transfer Characteristics



On-Resistance vs. Drain Current



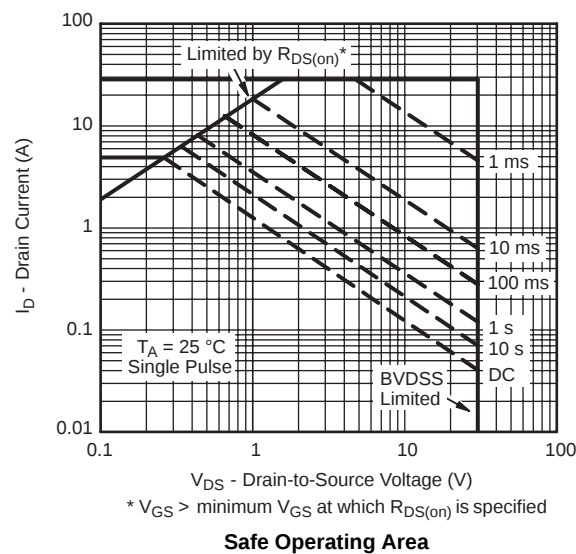
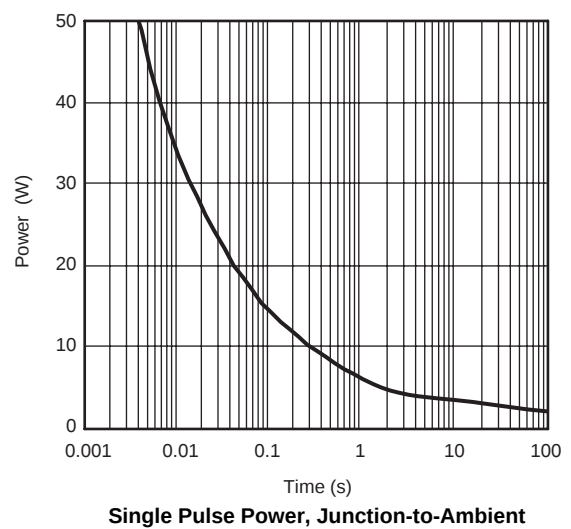
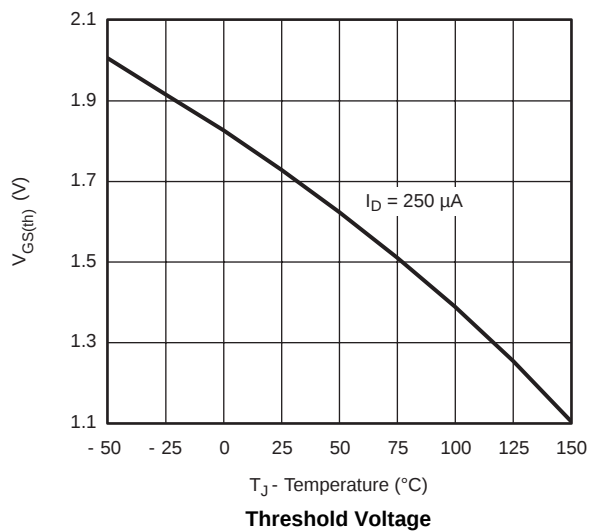
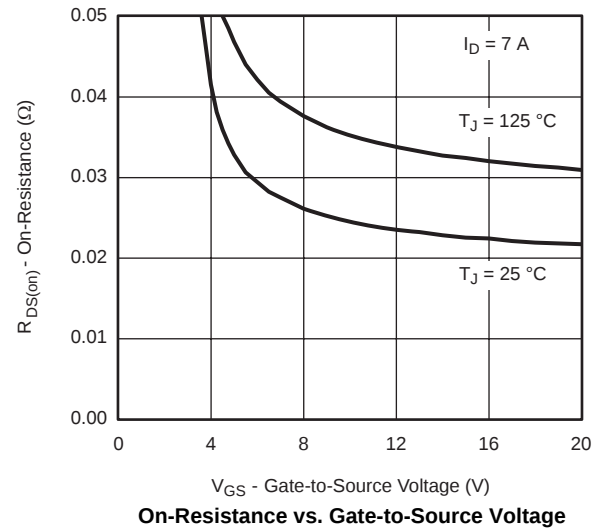
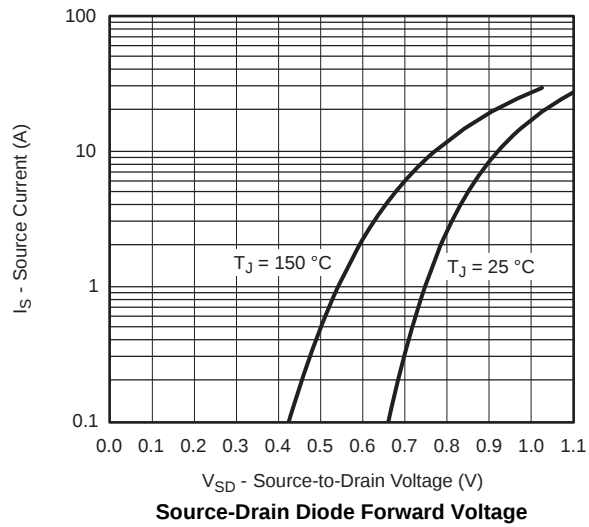
Capacitance



Gate Charge

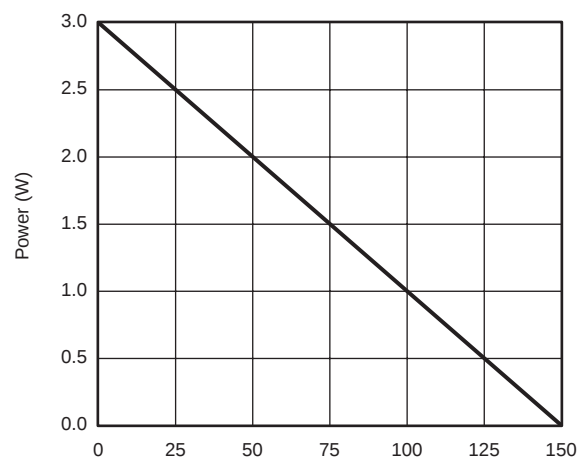


On-Resistance vs. Junction Temperature

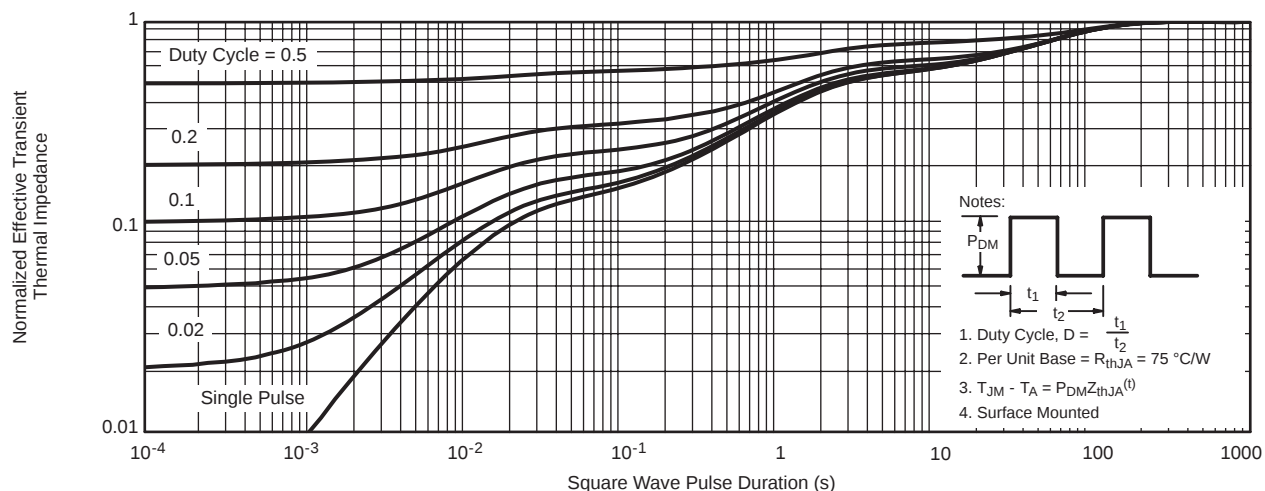
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Current Derating*

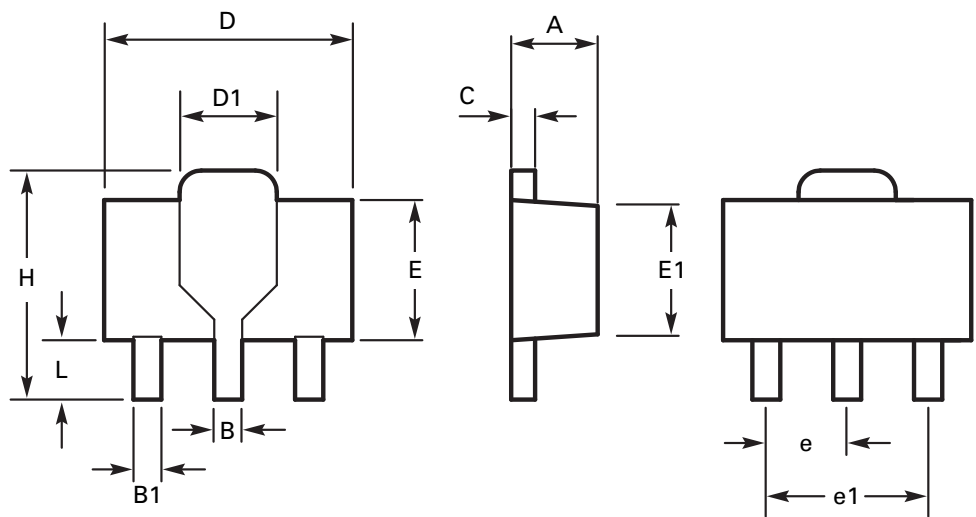
Power, Junction-to-Foot

Power Derating, Junction-to-Ambient

* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

Normalized Thermal Transient Impedance, Junction-to-Ambient

Normalized Thermal Transient Impedance, Junction-to-Foot

Package outline - SOT89



DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min	Max	Min	Max		Min	Max	Min	Max
A	1.40	1.60	0.550	0.630	E	2.29	2.60	0.090	0.102
B	0.44	0.56	0.017	0.022	E1	2.13	2.29	0.084	0.090
B1	0.36	0.48	0.014	0.019	e	1.50 BSC		0.059 BSC	
C	0.35	0.44	0.014	0.017	e1	3.00 BSC		0.118 BSC	
D	4.40	4.60	0.173	0.181	H	3.94	4.25	0.155	0.167
D1	1.62	1.83	0.064	0.072	L	0.89	1.20	0.035	0.047

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches

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